

Sample &

Buy









#### TL1431, TL1431M

SLVS062N-DECEMBER 1991-REVISED OCTOBER 2016

# TL1431 Precision Programmable Reference

Technical

Documents

### 1 Features

- 0.4% Initial Voltage Tolerance
- 0.2-Ω Typical Output Impedance
- Fast Turnon (500 ns)
- Sink Current Capability (1 mA to 100 mA)
- Low Reference Current (REF)
- Adjustable Output Voltage (V<sub>I(ref)</sub> to 36 V)

### 2 Applications

- Adjustable Voltage and Current Referencing
- Secondary Side Regulation in Flyback SMPSs
- Zener Replacement
- Voltage Monitoring
- Comparator With Integrated Reference

### 3 Description

The TL1431 device is a precision programmable reference with specified thermal stability over automotive, commercial, and military temperature ranges. The output voltage can be set to any value between V<sub>l(ref)</sub> (approximately 2.5 V) and 36 V with two external resistors (see Figure 25). This device has a typical output impedance of 0.2  $\Omega$ . Active output circuitry provides a sharp turnon characteristic, making the device an excellent replacement for Zener diodes and other types of references in applications such as onboard regulation, adjustable power supplies, and switching power supplies.

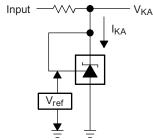
The TL1431C is characterized for operation over the commercial temperature range of 0°C to 70°C. The TL1431Q is characterized for operation over the full automotive temperature range of -40°C to 125°C. The TL1431M is characterized for operation over the full military temperature range of -55°C to 125°C.

PART NUMBER	PACKAGE	BODY SIZE (NOM)						
TL1431D	SOIC (8)	3.90 mm × 4.90 mm						
TL1431PW	TSSOP (8)	4.40 mm × 3.00 mm						
TL1431LP	TO-92 (3)	4.83 mm × 3.68 mm						
TL1431MJG	CDIP (8)	9.58 mm x 6.67 mm						
TL1431MFK	LCCC (20)	8.89 mm x 8.89 mm						

#### Device Information<sup>(1)</sup>

(1) For all available packages, see the orderable addendum at the end of the data sheet.

#### Simplified Schematic



Copyright © 2016, Texas Instruments Incorporated

# **Table of Contents**

1	Feat	tures 1
2	Арр	lications 1
3	Des	cription 1
4	Rev	ision History 2
5	Pin	Configuration and Functions 3
6	Spe	cifications 4
	6.1	Absolute Maximum Ratings 4
	6.2	ESD Ratings – TL1431C, TL1431Q 4
	6.3	Recommended Operating Conditions 4
	6.4	Thermal Information 4
	6.5	Electrical Characteristics – TL1431C 5
	6.6	Electrical Characteristics – TL1431Q 6
	6.7	Electrical Characteristics – TL1431M 7
	6.8	Typical Characteristics 8
7	Para	ameter Measurement Information 10
8	Deta	ailed Description 12
	8.1	Overview 12
	8.2	Functional Block Diagram 12
	8.3	Feature Description 13

	8.4	Device Functional Modes	. 14
9	Арр	lication and Implementation	15
	9.1	Application Information	. 15
	9.2	Typical Application	. 15
	9.3	System Examples	. 17
10	Pow	ver Supply Recommendations	20
11	Lay	out	20
	11.1		
	11.2	Layout Example	. 20
12	Dev	ice and Documentation Support	21
	12.1	Documentation Support	. 21
	12.2	Related Links	. 21
	12.3	Receiving Notification of Documentation Updates	5 <mark>2</mark> 1
	12.4	Community Resources	. 21
	12.5	Trademarks	. 21
	12.6	Electrostatic Discharge Caution	. 21
	12.7	Glossary	21
13	Mec	hanical, Packaging, and Orderable	
	Info	rmation	21

### **4** Revision History

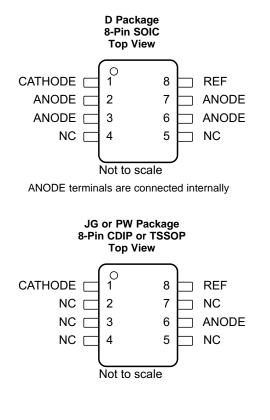
CI	hanges from Revision M (April 2012) to Revision N	Page
•	Added Device Information table, ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section	1
•	Deleted ORDERING INFORMATION table; see POA at the end of the data sheet	1
•	Changed R <sub>0JA</sub> for D, LP and PW package from: 97 °C/W to 114.7 °C/W (D), 140 °C/W to 157 °C/W (LP) and 149 °C/W to 172.4 °C/W (PW) in the <i>Thermal Information</i> table.	4
•	Changed R <sub>0JC(bot)</sub> for FK and JG package from: 5.61 °C/W to 9.5 °C/W (FK) and 14.5 °C/W to 9.5 °C/W (JG) in the <i>Thermal Information</i> table	4

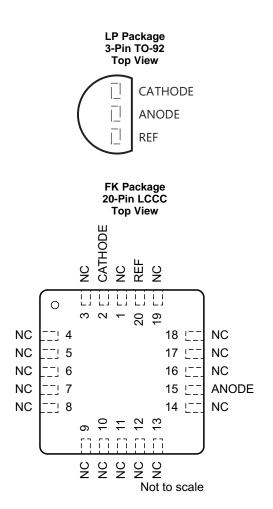
Changes from Revision L (October 2007) to Revision M			
•	Added Ammo option to the LP package in the ORDERING INFORMATION table.	2	

www.ti.com



### 5 Pin Configuration and Functions





#### **Pin Functions**

	PIN						
NAME	SOIC	CDIP, TSSOP	TO-92	LCCC	I/O	DESCRIPTION	
ANODE	2, 3, 6, 7	6	2	15	0	Common pin, normally connected to ground	
CATHODE	1	1	1	2	I/O	Shunt current/voltage input	
REF	8	8	3	20	I	Threshold relative to common ground	
NC	4, 5	2, 3, 4, 5, 7		1, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 16, 17, 18, 19	_	No internal connection	

#### TL1431, TL1431M

SLVS062N-DECEMBER 1991-REVISED OCTOBER 2016

TEXAS INSTRUMENTS

www.ti.com

### 6 Specifications

#### 6.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

	MIN	MAX	UNIT
Cathode voltage, $V_{KA}^{(2)}$		37	V
Continuous cathode current, I <sub>KA</sub>	-100	150	mA
Reference input current, I <sub>I(ref)</sub>	-0.05	10	mA
Lead temperature, 1.6 mm (1/16 in) from case for 10 s		260	°C
Junction temperature, T <sub>J</sub>		150	°C
Storage temperature, T <sub>stg</sub>	-65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) All voltage values are with respect to ANODE, unless otherwise noted.

### 6.2 ESD Ratings – TL1431C, TL1431Q

			VALUE	UNIT
V	Electroptotic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>		V
V <sub>(ESD)</sub>	Electrostatic discharge	Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±1000	V

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

#### 6.3 Recommended Operating Conditions

			MIN	MAX	UNIT
$V_{KA}$	Cathode voltage		V <sub>I(ref)</sub>	36	V
I <sub>KA</sub>	Cathode current		1	100	mA
		TL1431C	0	70	
T <sub>A</sub>	Operating free-air temperature	TL1431Q	-40	125	°C
		TL1431M	-55	125	

### 6.4 Thermal Information

			TL1431			TL1431M <sup>(2)</sup>		
	THERMAL METRIC <sup>(1)</sup>	LP (TO-92)	D (SOIC)	PW (TSSOP)	JG (CDIP)	FK (LCCC)	UNIT	
		3 PINS	8 PINS	8 PINS	8 PINS	20 PINS	_	
$R_{\thetaJA}$	Junction-to-ambient thermal resistance	157	114.7	172.4	—	_	°C/W	
$R_{\theta JC(top)}$	Junction-to-case (top) thermal resistance	80.7	59	55.2	69.7	55.5	°C/W	
$R_{\theta JB}$	Junction-to-board thermal resistance	_	55.4	100.8	99	54.2	°C/W	
ΨJT	Junction-to-top characterization parameter	24.6	12	5	—	_	°C/W	
ψјв	Junction-to-board characterization parameter	136.4	54.8	99	_	_	°C/W	
R <sub>0JC(bot)</sub>	Junction-to-case (bottom) thermal resistance			_	21	9.5	°C/W	

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report.

(2)  $R_{\theta JC}$  based on MIL-STD-883, and  $R_{\theta JB}$  based on JESD51.



#### 6.5 Electrical Characteristics – TL1431C

at specified free-air temperature and  $I_{KA}$  = 10 mA (unless otherwise noted)

× 10'

 $\Delta T_A$  is the rated operating temperature range of the device.

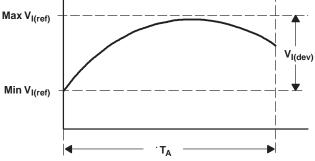
	PARAMETER	TEST CON	DITIONS	MIN	TYP	MAX	UNIT
V	Deference input veltage	V <sub>KA</sub> = V <sub>I(ref)</sub>	$T_A = 25^{\circ}C$	2490	2500	2510	mV
V <sub>I(ref)</sub>	Reference input voltage	(see Figure 13)	$T_A = 0^{\circ}C$ to $70^{\circ}C$	2480		2520	mv
V <sub>I(dev)</sub>	Deviation of reference input voltage over full temperature range <sup>(1)</sup>	$V_{KA} = V_{I(ref)}, T_A = 0^{\circ}C$ to (see Figure 13)	0 70°C		4	20	mV
$\frac{\Delta V_{\text{I(ref)}}}{\Delta V_{\text{KA}}}$	Ratio of change in reference input voltage to the change in cathode voltage	$\Delta V_{KA} = 3 V \text{ to } 36 V, T_A = 0^{\circ}\text{C to } 70^{\circ}\text{C}$ (see Figure 14)			-1.1	-2	mV/V
	Reference input current	R1 = 10 kΩ, R2 = ∞	$T_A = 25^{\circ}C$		1.5	2.5	
I <sub>I(ref)</sub>		(see Figure 14)	$T_A = 0^{\circ}C$ to $70^{\circ}C$			3	μA
I <sub>I(dev)</sub>	Deviation of reference input current over full temperature range <sup>(1)</sup>	R1 = 10 kΩ, R2 = ∞, T <sub>A</sub> (see Figure 14)	= 0°C to 70°C		0.2	1.2	μA
I <sub>min</sub>	Minimum cathode current for regulation	$V_{KA} = V_{I(ref)}, T_A = 25^{\circ}C$	(see Figure 13)		0.45	1	mA
	Off state esthade surrent	$V_{KA} = 36 V, V_{I(ref)} = 0$	$T_A = 25^{\circ}C$		0.18	0.5	
l <sub>off</sub>	Off-state cathode current	(see Figure 15)	$T_A = 0^{\circ}C$ to $70^{\circ}C$			2	μA
z <sub>KA</sub>	Output impedance <sup>(2)</sup>	$V_{KA} = V_{I(ref)}, f \le 1 \text{ kHz},$ $I_{KA} = 1 \text{ mA to 100 mA}, T_A = 25^{\circ}\text{C}$ (see Figure 13)			0.2	0.4	Ω

The deviation parameters  $V_{I(dev)}$  and  $I_{I(dev)}$  are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage  $\alpha_{VI(ref)}$  is defined as: (1)

$$\alpha_{\text{VI(ref)}} \left| \left( \frac{\text{ppm}}{^{\circ}\text{C}} \right) = \frac{\left( \frac{1(\text{deV})}{^{\vee}\text{VI(ref)} \text{ at } 25^{\circ}\text{C}} \right)}{^{\top}\text{T}_{\text{A}}}$$

where:

(2)



 $\begin{array}{l} \alpha_{VI(ref)} \text{ is positive or negative, depending on whether minimum } V_{I(ref)} \text{ or maximum } V_{I(ref)}, \text{ respectively, occurs at the lower temperature.} \\ \hline \\ \text{The output impedance is defined as:} & |z_{kA}| = \frac{\Delta V_{kA}}{\Delta I_{kA}} \\ \hline \\ \text{When the device is operating with two external resistors (see Figure 2), the total dynamic impedance of the circuit is given by:} \\ |z'| = \frac{\Delta V}{\Delta I}, \text{ which is approximately equal to } |z_{kA}| \left(1 + \frac{R1}{R2}\right). \end{array}$ 

SLVS062N-DECEMBER 1991-REVISED OCTOBER 2016

www.ti.com

STRUMENTS

AS

### 6.6 Electrical Characteristics – TL1431Q

at specified free-air temperature and  $I_{KA}$  = 10 mA (unless otherwise noted)

	PARAMETER	TEST CON	IDITIONS	MIN	TYP	MAX	UNIT
V	Deference innut veltere	V <sub>KA</sub> = V <sub>I(ref)</sub>	T <sub>A</sub> = 25°C	2490	2500	2510	10
V <sub>I(ref)</sub>	Reference input voltage	(see Figure 13)	$T_A = -40^{\circ}C$ to $125^{\circ}C$	2470		2530	mV
V <sub>I(dev)</sub>	Deviation of reference input voltage over full temperature range <sup>(1)</sup>	$V_{KA} = V_{I(ref)}, T_A = -40$ °C t (see Figure 13)	o 125°C		17	55	mV
$\frac{\Delta V_{\text{I(ref)}}}{\Delta V_{\text{KA}}}$	Ratio of change in reference input voltage to the change in cathode voltage	$\Delta V_{KA} = 3 V \text{ to } 36 V, T_A = (\text{see Figure 14})$	$\Delta V_{KA} = 3 \text{ V to } 36 \text{ V}, \text{ T}_{A} = -40^{\circ}\text{C to } 125^{\circ}\text{C}$ (see Figure 14)		-1.1	-2	mV/V
	Deference input ourrent	R1 = 10 kΩ, R2 = ∞	T <sub>A</sub> = 25°C		1.5	2.5 4	
I <sub>I(ref)</sub>	Reference input current	(see Figure 14)	$T_A = -40^{\circ}C$ to $125^{\circ}C$				μΑ
I <sub>I(dev)</sub>	Deviation of reference input current over full temperature range <sup>(1)</sup>	R1 = 10 kΩ, R2 = ∞, T <sub>A</sub> = (see Figure 14)	-40°C to 125°C		0.5	2	μA
I <sub>min</sub>	Minimum cathode current for regulation	$V_{KA} = V_{I(ref)}, T_A = 25^{\circ}C$ (s	ee Figure 13)		0.45	1	mA
	Off state astheds summat	$V_{KA} = 36 V, V_{I(ref)} = 0$	T <sub>A</sub> = 25°C		0.18	0.5	
I <sub>off</sub>	Off-state cathode current	(see Figure 15)	$T_A = -40^{\circ}C$ to $125^{\circ}C$			2	μA
z <sub>KA</sub>	Output impedance <sup>(2)</sup>	$V_{KA} = V_{I(ref)}, f \le 1 \text{ kHz},$ $I_{KA} = 1 \text{ mA to 100 mA}, T_A = 25^{\circ}\text{C}$ (see Figure 13)			0.2	0.4	Ω

The deviation parameters  $V_{I(dev)}$  and  $I_{I(dev)}$  are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage  $\alpha_{VI(ref)}$  is defined as: (1) (dev)

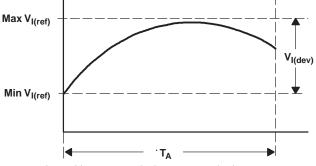
$$\left| \alpha_{\text{vi(ref)}} \right| \left( \frac{\text{ppm}}{\text{°C}} \right) = \frac{\left( \frac{1}{\text{V}_{\text{I(ref)}} \text{ at } 25^{\circ}\text{C}} \right)}{\text{T}_{\text{V}}}$$

where:

 $\Delta T_A$  is the rated operating temperature range of the device.

T,

× 10<sup>6</sup>



 $\alpha_{Vl(ref)} \text{ is positive or negative, depending on whether minimum } V_{l(ref)} \text{ or maximum } V_{l(ref)}, \text{ respectively, occurs at the lower temperature.}$ The output impedance is defined as:  $|z_{\kappa A}| = \frac{\Delta V_{\kappa A}}{\Delta I_{\kappa A}}$ When the device is operating with two external resistors (see Figure 2), the total dynamic impedance of the circuit is given by:  $|z'| = \frac{\Delta V}{\Delta I}$ , which is approximately equal to  $|z_{\kappa A}| \left(1 + \frac{R1}{R2}\right)$ . (2)

6



### 6.7 Electrical Characteristics – TL1431M

at specified free-air temperature and  $I_{KA} = 10$  mA (unless otherwise noted)

	PARAMETER	TEST CO	NDITIONS	MIN	TYP	MAX	UNIT
	Deference incut veltere	$V_{KA} = V_{I(ref)}$	T <sub>A</sub> = 25°C	2475	2500	2540	
V <sub>I(ref)</sub>	Reference input voltage	(see Figure 13)	$T_A = -55^{\circ}C$ to $125^{\circ}C$	2460		2550	mV
V <sub>I(dev)</sub>	Deviation of reference input voltage over full temperature range <sup>(1)</sup>	$V_{KA} = V_{I(ref)}, T_A = -55^{\circ}C$ (see Figure 13)		17	55 <sup>(2)</sup>	mV	
$\frac{\Delta V_{\text{I(ref)}}}{\Delta V_{\text{KA}}}$	Ratio of change in reference input voltage to the change in cathode voltage	$\Delta V_{KA} = 3 V \text{ to } 36 V, T_A = $ (see Figure 14)		-1.1	-2	mV/V	
	Deference input ourrent	R1 = 10 kΩ, R2 = ∞	T <sub>A</sub> = 25°C		1.5	2.5	
I <sub>I(ref)</sub>	Reference input current	(see Figure 14)	$T_A = -55^{\circ}C$ to $125^{\circ}C$			5	μA
I <sub>I(dev)</sub>	Deviation of reference input current over full temperature range <sup>(1)</sup>	R1 = 10 kΩ, R2 = ∞, T <sub>A</sub> = (see Figure 14)		0.5	3 <sup>(2)</sup>	μA	
I <sub>min</sub>	Minimum cathode current for regulation	$V_{KA} = V_{I(ref)}, T_A = 25^{\circ}C$ (s	see Figure 13)		0.45	1	mA
	Off state astheds summart	$V_{KA} = 36 V, V_{I(ref)} = 0$	$T_A = 25^{\circ}C$		0.18	0.5	۵
I <sub>off</sub>	Off-state cathode current	(see Figure 15)	$T_A = -55^{\circ}C$ to $125^{\circ}C$			2	μA
z <sub>KA</sub>	Output impedance <sup>(3)</sup>	$V_{KA} = V_{I(ref)}, f \le 1 \text{ kHz},$ $I_{KA} = 1 \text{ mA to 100 mA, T},$ (see Figure 13)		0.2	0.4	Ω	

The deviation parameters  $V_{I(dev)}$  and  $I_{I(dev)}$  are defined as the differences between the maximum and minimum values obtained over the rated temperature range. The average full-range temperature coefficient of the reference input voltage  $\alpha_{VI(ref)}$  is defined as: (1) l(dev)

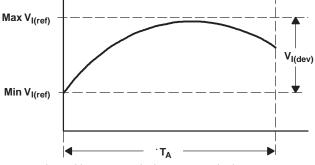
$$\left| \alpha_{\text{vl(ref)}} \right| \left( \frac{\text{ppm}}{^{\circ}\text{C}} \right) = \frac{\left( \frac{1}{^{\circ}\text{V}_{\text{l(ref)}} \text{ at } 25^{\circ}\text{C}} \right)}{T_{\text{c}}}$$

where:

 $\Delta T_{\text{A}}$  is the rated operating temperature range of the device.

Τ,

× 10<sup>6</sup>



(2)

 $\begin{aligned} \alpha_{VI(ref)} \text{ is positive or negative, depending on whether minimum } V_{I(ref)} \text{ or maximum } V_{I(ref)}, \text{ respectively, occurs at the lower temperature.} \\ \text{On products compliant to MIL-PRF-38535, this parameter is not production tested.} \\ \text{The output impedance is defined as:} & |z_{\kappa A}| = \frac{\Delta V_{\kappa A}}{\Delta I_{\kappa A}} \\ \text{When the device is operating with two external resistors (see Figure 2), the total dynamic impedance of the circuit is given by:} \\ |z'| = \frac{\Delta V}{\Delta I}, \text{ which is approximately equal to } |z_{\kappa A}| \left(1 + \frac{R1}{R2}\right). \end{aligned}$ (3)

#### TL1431, TL1431M

SLVS062N-DECEMBER 1991-REVISED OCTOBER 2016

www.ti.com

**ISTRUMENTS** 

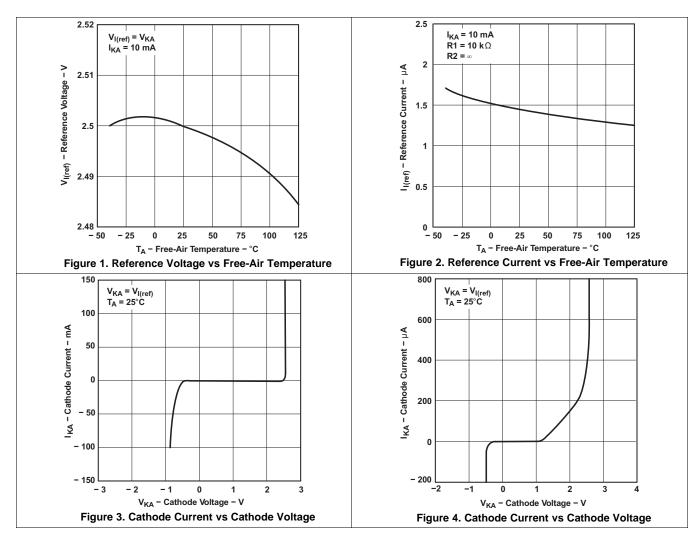
EXAS

### 6.8 Typical Characteristics

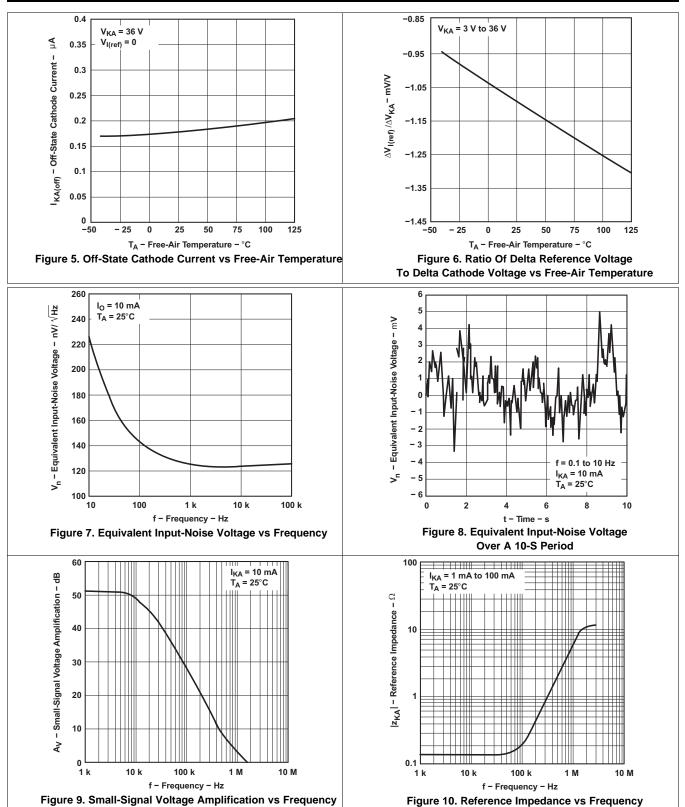
Data at high and low temperatures are applicable only within the recommended operating free-air temperature ranges of the various devices.

GRAPH	FIGURE
Reference voltage vs Free-air temperature	Figure 1
Reference current vs Fire-air temperature	Figure 2
Cathode current vs Cathode voltage	Figure 3, Figure 4
Off-state cathode current vs Free-air temperature	Figure 5
Ratio of delta reference voltage to delta cathode voltage vs Free-air temperature	Figure 6
Equivalent input-noise voltage vs Frequency	Figure 7
Equivalent input-noise voltage over a 10-second period	Figure 8
Small-signal voltage amplification vs Frequency	Figure 9
Reference impedance vs Frequency	Figure 10
Pulse response	Figure 11
Stability boundary conditions	Figure 12



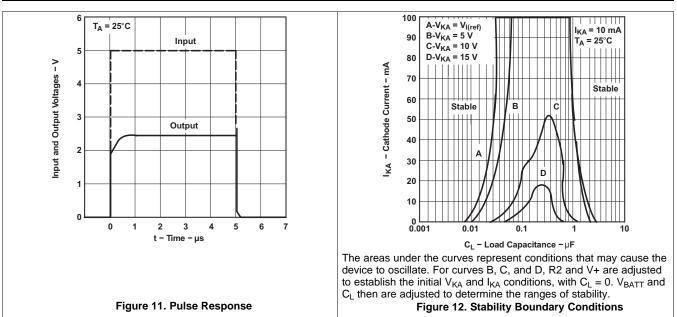




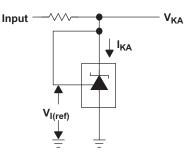


#### TL1431, TL1431M

SLVS062N-DECEMBER 1991-REVISED OCTOBER 2016



### 7 Parameter Measurement Information





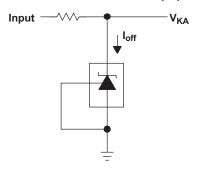
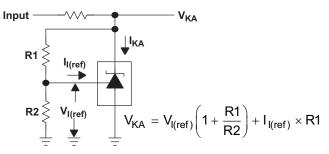


Figure 15. Test Circuit For Ioff

Submit Documentation Feedback



Texas

**INSTRUMENTS** 

www.ti.com



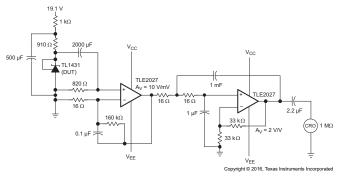


Figure 16. Test Circuit For 0.1-Hz To 10-Hz Equivalent Input-Noise Voltage



Output

Parameter Measurement Information (continued)

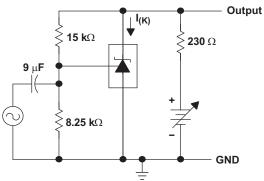
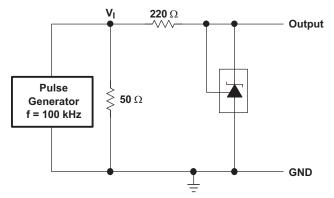
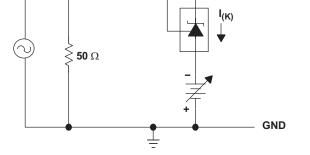


Figure 17. Test Circuit For Voltage Amplification

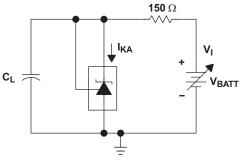




**1 k**Ω

 $\Lambda \Lambda \Lambda$ 

Figure 18. Test Circuit For Reference Impedance



Test Circuit for Curve A

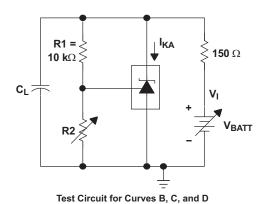


Figure 19. Test Circuit For Pulse Response

Figure 20. Test Circuits For Curves A Through D

Texas Instruments

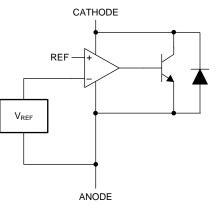
www.ti.com

### 8 Detailed Description

#### 8.1 Overview

The TL1431 device has proven ubiquity and versatility across a wide range of applications, ranging from power to signal path. This is due to its key components containing an accurate voltage reference and op amp, which are very fundamental analog building blocks. TL1431 is used in conjunction with its key components to behave as a single voltage reference, error amplifier, voltage clamp, or comparator with integrated reference. TL1431 can be operated and adjusted to cathode voltages from 2.5 V to 36 V, making this part optimum for a wide range of end equipments in industrial, auto, telecom, and computing. In order for this device to behave as a shunt regulator or error amplifier, >1 mA (Imin(max)) must be supplied in to the cathode pin. Under this condition, feedback can be applied from the Cathode and Ref pins to create a replica of the internal reference voltage. Various reference voltage options can be purchased with initial tolerances (at 25°C) of 0.4% and 1%. The TL1431C devices are characterized for operation from 0°C to 70°C, the TL1431Q devices are characterized for operation from -40°C to 125°C, and the TL1431M devices are characterized for operation from -55°C to 125°C.

### 8.2 Functional Block Diagram

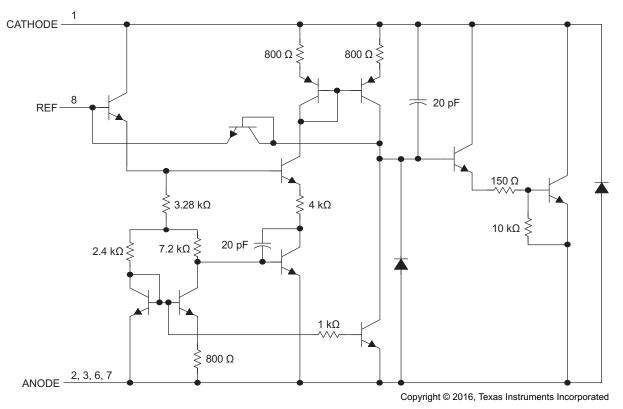


Copyright © 2016, Texas Instruments Incorporated

Figure 21. Equivalent Schematic



#### **Functional Block Diagram (continued)**



- (1) All component values are nominal.
- (2) Pin numbers shown are for the D package.



#### 8.3 Feature Description

TL1431 consists of an internal reference and amplifier that outputs a sink current base on the difference between the reference pin and the virtual internal pin. The sink current is produced by the internal Darlington pair, shown in Figure 22. A Darlington pair is used in order for this device to be able to sink a maximum current of 100 mA. When operated with enough voltage headroom ( $\geq 2.5$  V) and cathode current ( $I_{KA}$ ), TL1431 forces the reference pin to 2.5 V. However, the reference pin can not be left floating, as it needs  $I_{REF} \geq 5 \ \mu A$  (see *Electrical Characteristics – TL1431M*). This is because the reference pin is driven into an npn, which needs base current to operate properly. When feedback is applied from the cathode and reference pins, TL1431 behaves as a Zener diode, regulating to a constant voltage dependent on current being supplied into the cathode. This is due to the internal amplifier and reference entering the proper operating regions. The same amount of current needed in the above feedback situation must be applied to this device in open loop, servo, or error amplifying implementations in order for it to be in the proper linear region giving TL1431 enough gain. Unlike many linear regulators, TL1431 is internally compensated to be stable without an output capacitor between the cathode and anode. However, if desired an output capacitor can be used as a guide to assist in choosing the correct capacitor to maintain stability.

# TL1431, TL1431M

SLVS062N-DECEMBER 1991-REVISED OCTOBER 2016



www.ti.com

#### 8.4 Device Functional Modes

#### 8.4.1 Open Loop (Comparator)

When the cathode or output voltage or current of TL1431 is not being fed back to the reference or input pin in any form, this device is operating in open loop. With proper cathode current ( $I_{KA}$ ) applied to this device, TL1431 has the characteristics shown in Figure 22. With such high gain in this configuration, TL1431 is typically used as a comparator. With the reference integrated makes TL1431 the preferred choice when users are trying to monitor a certain level of a single signal.

#### 8.4.2 Closed Loop

When the cathode or output voltage or current of TL1431 is being fed back to the reference or input pin in any form, this device is operating in closed loop. The majority of applications involving TL1431 use it in this manner to regulate a fixed voltage or current. The feedback enables this device to behave as an error amplifier, computing a portion of the output voltage and adjusting it to maintain the desired regulation. This is done by relating the output voltage back to the reference pin in a manner to make it equal to the internal reference voltage, which can be accomplished through resistive or direct feedback.



### 9 Application and Implementation

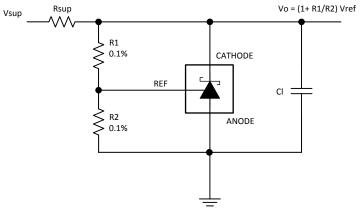
#### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

#### 9.1 Application Information

As the TL1431 device has many applications and setups, there are many situations that this datasheet cannot characterize in detail. The linked application notes help the designer make the best choices when using this part. *Understanding Stability Boundary Conditions Charts in TL431, TL432 Data Sheet* (SLVA482) provides a deeper understanding of this devices stability characteristics and aid the user in making the right choices when choosing a load capacitor. *Setting the Shunt Voltage on an Adjustable Shunt Regulator* (SLVA445) assists designers in setting the shunt voltage to achieve optimum accuracy for this device.

#### 9.2 Typical Application



Copyright © 2016, Texas Instruments Incorporated

Figure 23. Comparator Application Schematic

#### 9.2.1 Design Requirements

For this design example, use the parameters listed in Table 2 as the input parameters.

5								
PARAMETER	VALUE							
Reference initial accuracy	0.4%							
Supply voltage	48 V							
Cathode current (I <sub>K</sub> )	50 µA							
Output voltage level	2.5 V to 36 V							
Load capacitance	1 nF							
Feedback resistor values and accuracy (R1 and R2)	10 kΩ							

#### 9.2.2 Detailed Design Procedure

When using TL1431 as a shunt regulator, determine the following:

- Input voltage range
- Temperature range
- Total accuracy
- Cathode current



- Reference initial accuracy
- Output capacitance

#### 9.2.2.1 Programming Output/Cathode Voltage

To program the cathode voltage to a regulated voltage a resistive bridge must be shunted between the cathode and anode pins with the mid point tied to the reference pin. This can be seen in Figure 23, with R1 and R2 being the resistive bridge. The cathode/output voltage in the shunt regulator configuration can be approximated by the equation shown in Figure 23. The cathode voltage can be more accurately determined by taking in to account the cathode current with Equation 1.

$$Vo = (1 + R1 / R2) \times V_{REF} - I_{REF} \times R1$$

(1)

For this equation to be valid, TL1431 must be fully biased so that it has enough open loop gain to mitigate any gain error. This can be done by meeting the Imin specification denoted in *Electrical Characteristics – TL1431M*.

#### 9.2.2.2 Total Accuracy

When programming the output above unity gain ( $V_{KA}=V_{REF}$ ), TL1431 is susceptible to other errors that may effect the overall accuracy beyond  $V_{REF}$ . These errors include:

- R1 and R2 accuracies
- V<sub>I(dev)</sub> Change in reference voltage over temperature
- $\Delta V_{REF} / \Delta V_{KA}$  Change in reference voltage to the change in cathode voltage
- |z<sub>KA</sub>| Dynamic impedance, causing a change in cathode voltage with cathode current

Worst case cathode voltage can be determined taking all of the variables in to account.

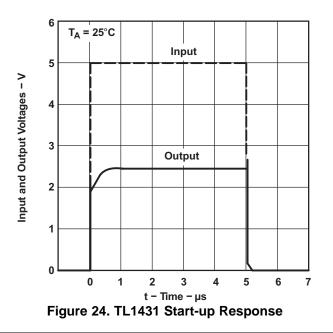
#### 9.2.2.3 Stability

Though TL1431 is stable with no capacitive load, the device that receives the shunt regulator's output voltage could present a capacitive load that is within the TL1431 region of stability, shown in Figure 12. Also, designers may use capacitive loads to improve the transient response or for power supply decoupling. When using additional capacitance between Cathode and Anode, refer to Figure 12.

#### 9.2.2.4 Start-up Time

As shown in Figure 24, TL1431 has a fast response up to approximately 2 V and then slowly charges to its programmed value. This is due to the compensation capacitance the TL1431 has to meet its stability criteria. Despite the secondary delay, TL1431 still has a fast response suitable for many clamp applications.

#### 9.2.3 Application Curve



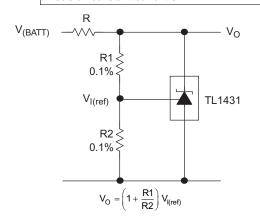


#### 9.3 System Examples

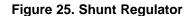
Table 3 lists example circuits of the TL1431.

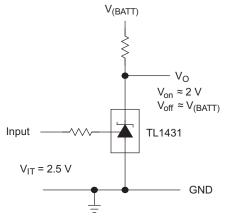
APPLICATION	FIGURE							
Shunt regulator	Figure 25							
Single-supply comparator with temperature-compensated threshold	Figure 26							
Precision high-current series regulator	Figure 27							
Output control of a three-terminal fixed regulator	Figure 28							
Higher-current shunt regulator	Figure 29							
Crowbar	Figure 30							
Precision 5-V, 1.5-A, 0.5% regulator	Figure 31							
5-V precision regulator	Figure 32							
PWM converter with 0.5% reference	Figure 33							
Voltage monitor	Figure 34							
Delay timer	Figure 35							
Precision current limiter	Figure 36							
Precision constant-current sink	Figure 37							





Copyright © 2016, Texas Instruments Incorporated R must provide cathode current ≥1 mA to the TL1431 at minimum  $V_{(BATT)}$ .





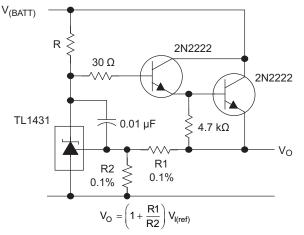
Copyright © 2016, Texas Instruments Incorporated

#### Figure 26. Single-Supply Comparator With Temperature-Compensated Threshold



TL1431, TL1431M

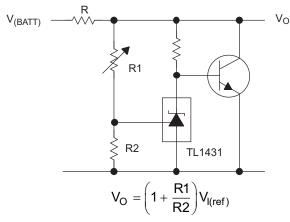
SLVS062N-DECEMBER 1991-REVISED OCTOBER 2016



Copyright © 2016, Texas Instruments Incorporated

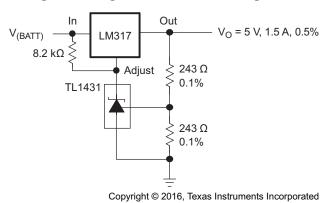
R must provide cathode current  $\geq$ 1 mA to the TL1431 at minimum V<sub>(BATT)</sub>.

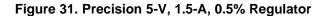
### Figure 27. Precision High-Current Series Regulator

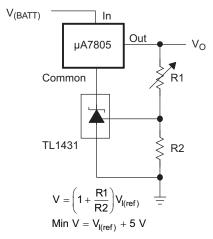


Copyright © 2016, Texas Instruments Incorporated

#### Figure 29. Higher-Current Shunt Regulator

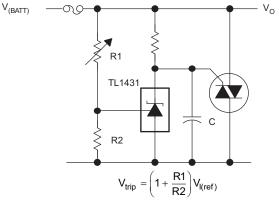






Copyright © 2016, Texas Instruments Incorporated

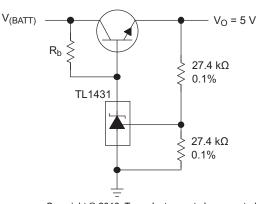
#### Figure 28. Output Control Of A Three-Terminal Fixed Regulator



Copyright © 2016, Texas Instruments Incorporated

See the stability boundary conditions in Figure 12 to determine allowable values for C.

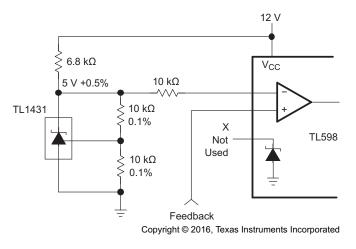
#### Figure 30. Crowbar

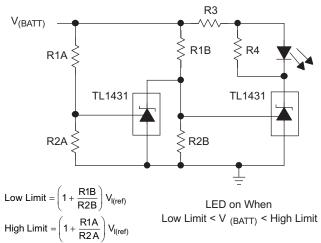


Copyright © 2016, Texas Instruments Incorporated  $R_b$  must provide cathode current ≥1 mA to the TL1431.

Figure 32. 5-V Precision Regulator



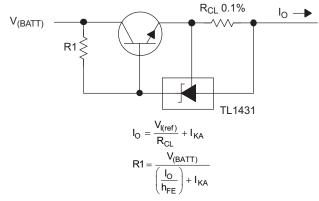




Copyright © 2016, Texas Instruments Incorporated

Select R3 and R4 to provide the desired LED intensity and cathode current  $\geq$ 1 mA to the TL1431.

Figure 34. Voltage Monitor



Copyright © 2016, Texas Instruments Incorporated

#### Figure 36. Precision Current Limiter

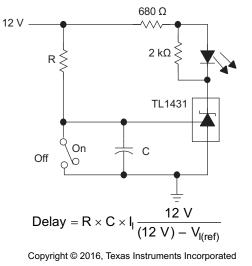
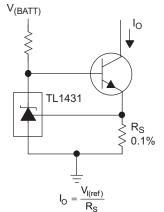


Figure 33. PWM Converter With 0.5% Reference

#### Figure 35. Delay Timer



Copyright © 2016, Texas Instruments Incorporated Figure 37. Precision Constant-Current Sink

### TL1431, TL1431M

SLVS062N-DECEMBER 1991-REVISED OCTOBER 2016

www.ti.com

### 10 Power Supply Recommendations

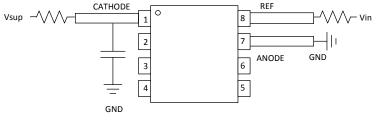
When using TL1431 as a linear regulator to supply a load, designers typically use a bypass capacitor on the output/cathode pin. When doing this, be sure that the capacitance is within the stability criteria shown in Figure 12. To not exceed the maximum cathode current, ensure the supply voltage is current limited. Also, be sure to limit the current being driven into the Ref pin, as not to exceed it's absolute maximum rating. For applications shunting high currents, pay attention to the cathode and anode trace lengths, adjusting the width of the traces to have the proper current density.

### 11 Layout

#### 11.1 Layout Guidelines

Bypass capacitors must be placed as close to the part as possible. Current-carrying traces need to have widths appropriate for the amount of current they are carrying; in the case of the TL1431, these currents are low.

### 11.2 Layout Example



Copyright © 2016, Texas Instruments Incorporated

Figure 38. PW Package Layout Example



### **12 Device and Documentation Support**

#### **12.1** Documentation Support

#### 12.1.1 Related Documentation

For related documentation see the following:

- Understanding Stability Boundary Conditions Charts in TL431, TL432 Data Sheet (SLVA482)
- Setting the Shunt Voltage on an Adjustable Shunt Regulator (SLVA445)

#### 12.2 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

#### **Table 4. Related Links**

PARTS	PRODUCT FOLDER	SAMPLE & BUY	TECHNICAL DOCUMENTS	TOOLS & SOFTWARE	SUPPORT & COMMUNITY
TL1431	Click here	Click here	Click here	Click here	Click here
TL1431M	Click here	Click here	Click here	Click here	Click here

#### 12.3 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

#### 12.4 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's Terms of Use.

TI E2E<sup>™</sup> Online Community *TI's Engineer-to-Engineer (E2E) Community.* Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

**Design Support TI's Design Support** Quickly find helpful E2E forums along with design support tools and contact information for technical support.

#### 12.5 Trademarks

E2E is a trademark of Texas Instruments. All other trademarks are the property of their respective owners.

#### 12.6 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

#### 12.7 Glossary

SLYZ022 — TI Glossary.

This glossary lists and explains terms, acronyms, and definitions.

### 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

Copyright © 1991–2016, Texas Instruments Incorporated



### PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9962001Q2A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9962001Q2A TL1431MFKB
5962-9962001QPA	Active	Production	CDIP (JG)   8	50   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	9962001QPA TL1431M
TL1431CD	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	1431C
TL1431CD.A	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1431C
TL1431CDR	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	1431C
TL1431CDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1431C
TL1431CLP	Active	Production	TO-92 (LP)   3	1000   BULK	Yes	SN	N/A for Pkg Type	0 to 70	TL1431C
TL1431CLP.A	Active	Production	TO-92 (LP)   3	1000   BULK	Yes	SN	N/A for Pkg Type	-40 to 125	TL1431C
TL1431CLPME3	Active	Production	TO-92 (LP)   3	2000   LARGE T&R	Yes	SN	N/A for Pkg Type	0 to 70	TL1431C
TL1431CLPME3.A	Active	Production	TO-92 (LP)   3	2000   LARGE T&R	Yes	SN	N/A for Pkg Type	-40 to 125	TL1431C
TL1431CLPR	Active	Production	TO-92 (LP)   3	2000   LARGE T&R	Yes	SN	N/A for Pkg Type	0 to 70	TL1431C
TL1431CLPR.A	Active	Production	TO-92 (LP)   3	2000   LARGE T&R	Yes	SN	N/A for Pkg Type	-40 to 125	TL1431C
TL1431CPWR	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU   SN	Level-1-260C-UNLIM	0 to 70	T1431
TL1431CPWR.A	Active	Production	TSSOP (PW)   8	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	T1431
TL1431MFK	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	TL1431MFK
TL1431MFK.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	TL1431MFK
TL1431MFKB	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9962001Q2A TL1431MFKB
TL1431MFKB.A	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9962001Q2A TL1431MFKB
TL1431MJG	Active	Production	CDIP (JG)   8	50   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	TL1431MJG
TL1431MJG.A	Active	Production	CDIP (JG)   8	50   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	TL1431MJG
TL1431MJGB	Active	Production	CDIP (JG)   8	50   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	9962001QPA TL1431M
TL1431MJGB.A	Active	Production	CDIP (JG)   8	50   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	9962001QPA TL1431M

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking
	(1)	(2)			(3)	(4)	(5)		(6)
TL1431QD	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1431Q
TL1431QD.A	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1431Q
TL1431QDG4	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1431Q
TL1431QDG4.A	Active	Production	SOIC (D)   8	75   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1431Q
TL1431QDR	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1431Q
TL1431QDR.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1431Q
TL1431QDRG4	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1431Q
TL1431QDRG4.A	Active	Production	SOIC (D)   8	2500   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 125	1431Q

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



#### OTHER QUALIFIED VERSIONS OF TL1431, TL1431M :

• Catalog : TL1431

- Automotive : TL1431-Q1, TL1431-Q1
- Enhanced Product : TL1431-EP, TL1431-EP
- Military : TL1431M
- Space : TL1431-SP, TL1431-SP

#### NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Military QML certified for Military and Defense Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application



Texas

\*All dimensions are nominal

www.ti.com

### TAPE AND REEL INFORMATION





#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

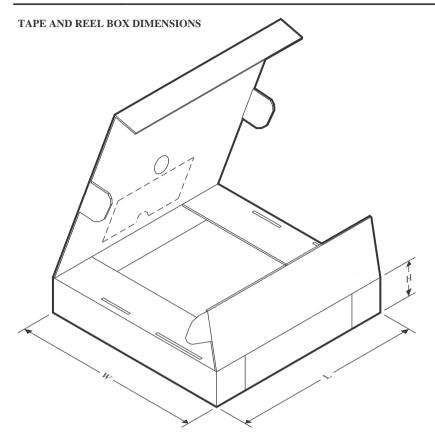


Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL1431CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL1431CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1
TL1431QDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL1431QDRG4	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1



# PACKAGE MATERIALS INFORMATION

23-May-2025



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL1431CDR	SOIC	D	8	2500	353.0	353.0	32.0
TL1431CPWR	TSSOP	PW	8	2000	356.0	356.0	35.0
TL1431QDR	SOIC	D	8	2500	353.0	353.0	32.0
TL1431QDRG4	SOIC	D	8	2500	350.0	350.0	43.0

### TEXAS INSTRUMENTS

www.ti.com

23-May-2025

### TUBE



### - B - Alignment groove width

*All dimensions are nominal								
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	Τ (μm)	B (mm)
5962-9962001Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
TL1431CD	D	SOIC	8	75	507	8	3940	4.32
TL1431CD.A	D	SOIC	8	75	507	8	3940	4.32
TL1431MFK	FK	LCCC	20	55	506.98	12.06	2030	NA
TL1431MFK.A	FK	LCCC	20	55	506.98	12.06	2030	NA
TL1431MFKB	FK	LCCC	20	55	506.98	12.06	2030	NA
TL1431MFKB.A	FK	LCCC	20	55	506.98	12.06	2030	NA
TL1431QD	D	SOIC	8	75	505.46	6.76	3810	4
TL1431QD.A	D	SOIC	8	75	505.46	6.76	3810	4
TL1431QDG4	D	SOIC	8	75	505.46	6.76	3810	4
TL1431QDG4.A	D	SOIC	8	75	505.46	6.76	3810	4

# **JG0008A**

# **PACKAGE OUTLINE**

### CDIP - 5.08 mm max height

CERAMIC DUAL IN-LINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing 2. This drawing is subject to change without notice.3. This package can be hermetically sealed with a ceramic lid using glass frit.

- Index point is provided on cap for terminal identification.
   Falls within MIL STD 1835 GDIP1-T8



# JG0008A

# **EXAMPLE BOARD LAYOUT**

# CDIP - 5.08 mm max height

CERAMIC DUAL IN-LINE PACKAGE





# FK 20

### 8.89 x 8.89, 1.27 mm pitch

# **GENERIC PACKAGE VIEW**

## LCCC - 2.03 mm max height

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary. Refer to the product data sheet for package details.





# D0008A



# **PACKAGE OUTLINE**

### SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



#### NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.

- 2. This drawing is subject to change without notice.
- 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
- 4. This dimension does not include interlead flash.
- 5. Reference JEDEC registration MS-012, variation AA.



# D0008A

# **EXAMPLE BOARD LAYOUT**

## SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# D0008A

# **EXAMPLE STENCIL DESIGN**

# SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

9. Board assembly site may have different recommendations for stencil design.



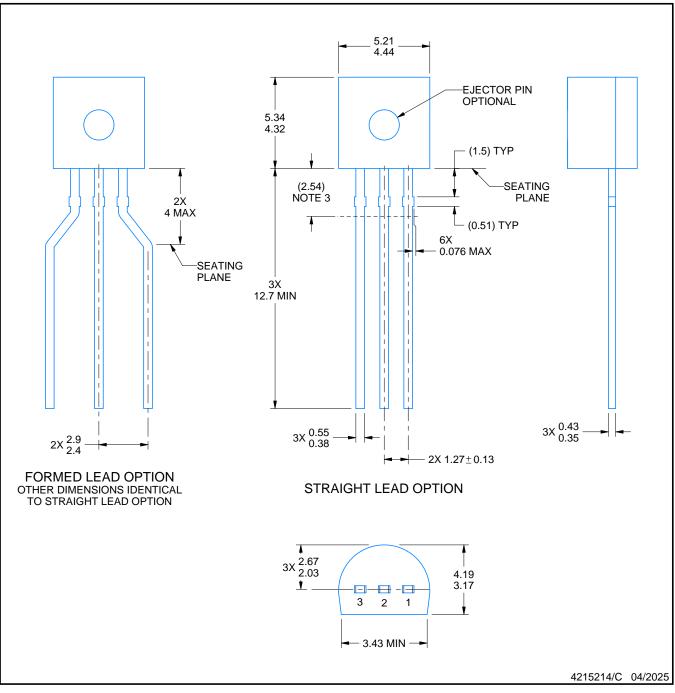
# LP0003A



# **PACKAGE OUTLINE**

### TO-92 - 5.34 mm max height

TO-92



#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice.
- Lead dimensions are not controlled within this area.
   Reference JEDEC TO-226, variation AA.
- 5. Shipping method:

  - a. Straight lead option available in bulk pack only.b. Formed lead option available in tape and reel or ammo pack.
  - c. Specific products can be offered in limited combinations of shipping medium and lead options.
  - d. Consult product folder for more information on available options.

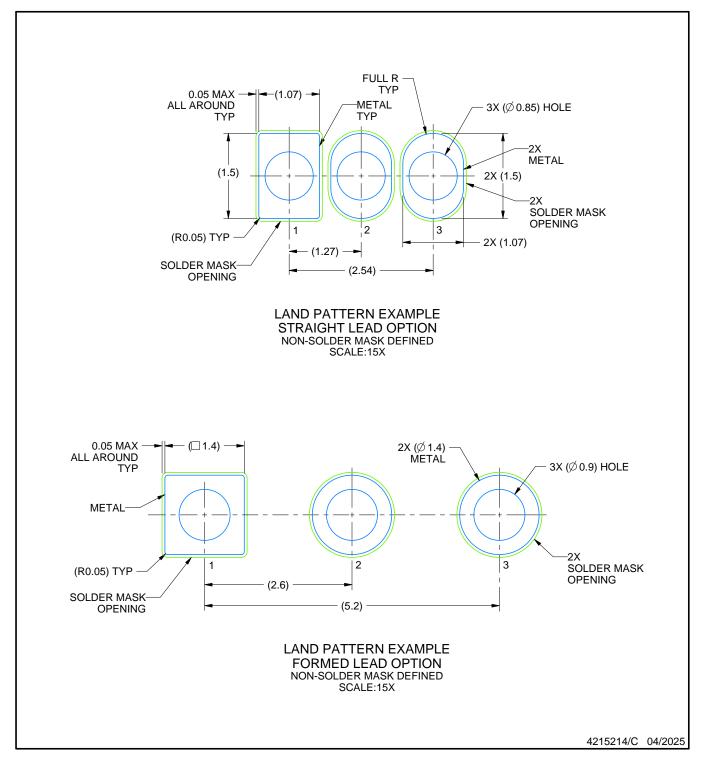


# LP0003A

# **EXAMPLE BOARD LAYOUT**

### TO-92 - 5.34 mm max height

TO-92



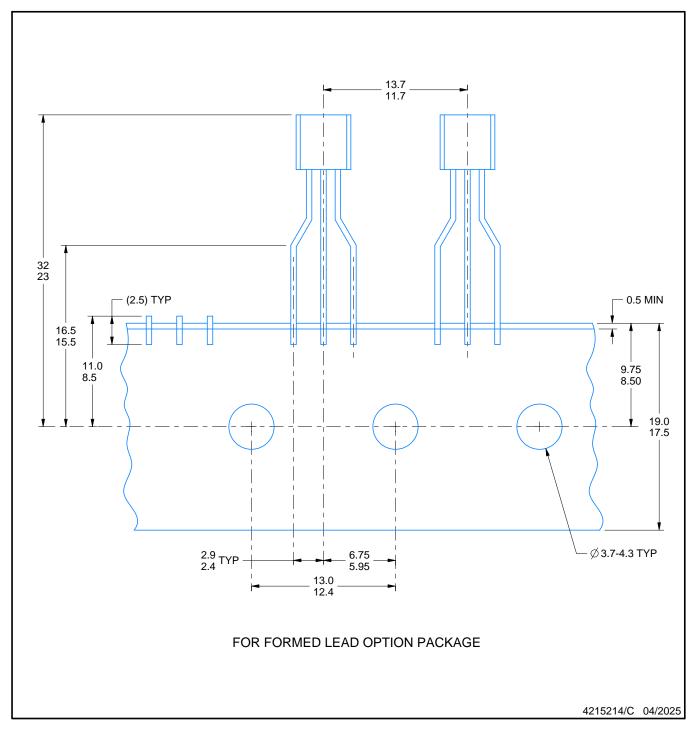


# LP0003A

# TAPE SPECIFICATIONS

# TO-92 - 5.34 mm max height

TO-92





# **PW0008A**



# **PACKAGE OUTLINE**

# TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M. 2. This drawing is subject to change without notice. 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153, variation AA.



# PW0008A

# **EXAMPLE BOARD LAYOUT**

# TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



# PW0008A

# **EXAMPLE STENCIL DESIGN**

# TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



NOTES: (continued)

9. Board assembly site may have different recommendations for stencil design.



<sup>8.</sup> Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

### IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATA SHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

TI objects to and rejects any additional or different terms you may have proposed.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2025, Texas Instruments Incorporated